

A close-up, angled view of a silicon microchip, showing its intricate circuitry and grid-like patterns. The chip is illuminated with a blue light, creating a high-tech, futuristic aesthetic. The right side of the image is partially obscured by a solid blue overlay containing text.

Small Talk 2024 Investor Day

Abbreviations

Investor Day 2024 - Abbreviations

Abbreviation	Meaning	Abbreviation	Meaning
μm	Micrometer	CBA	CMOS Bonded Array
1D	1 dimensional	CD	Critical Dimension
2D	2 dimensional	CDU	Critical Dimension Uniformity
3D	3 Dimensional	CFET	Complementary Field Effect Transistor
AEX	Amsterdam Exchange index	CMD	Capital Markets Day
AI	Artificial Intelligence	CMOS	Complementary metal oxide semiconductor
ArF	Argon Fluoride DUV system	CN	China
ArFi	Argon Fluoride Immersion DUV system	CO2	Carbon dioxide
Bn	billion	COG	Cost Of Goods
BSPN	BackSide Power Delivery Network	CPU	Central Processing Unit
CAGR	Compound annual growth rate	D&E	Development & Engineering
capex	Capital Expenditure	DDR	Double Data Rate
CAR	Chemical Amplified Resist	DP	Double Patterning

Investor Day 2024 - Abbreviations

Abbreviation	Meaning
DRAM	Dynamic Random Access Memory
DUV	Deep Ultraviolet
EBIT	Earnings Before Interest and Taxes
EPE	Edge Placement Error
EPS	Earnings per share
ESG	Environmental Social Governance
EUV	Extreme Ultraviolet
EXE	0.55 NA EUV platform
FinFET	FIN Field Effect Transistor
FLOPS	Floating-point operations per second
GDP	Gross Domestic Product
GM	Gross Margin
GPU	Graphics Processing Unit

Abbreviation	Meaning
HBM	High Bandwidth Memory
HMI	Hermes Microvision Inc.
HPC	High Power Compute
HVM	High Volume Manufacturing
IBM	Installed Base Management
IRL	Ireland
ITF	imec Technology Forum
KR	South-Korea
KrF	Krypton Fluoride DUV system
Kwspm	x1000 wafer starts per month
LCDU	Local Critical Dimension Uniformity
LEn	Litho Etch
LEn	Litho Etch; n number repeats

Investor Day 2024 - Abbreviations

Abbreviation	Meaning	Abbreviation	Meaning
Mainstream Logic	>7 nm nodes (non EUV)	PEP	Productivity Enhancement Package
MBI	Multi Beam inspection	PIM	Processing In Memory
MMO	Matched Machine Overlay	POB	Projection Optics Box
MW	Mega Watt	PP	Pre-Pulse
NA	Numerical Aperture	QP	Quadruple Patterning
NAND	Not AND - nonvolatile memory	R&D	Research & Development
nm	nanometer	RP	Rarefaction Pulse
NXE	0.33 NA EUV platform	S&P 500	Standard & Poor's 500 index
OEE	Overall Equipment Efficiency	SA	Self Aligned
OPEX	Operating Expense	SG&A	Selling, General and Administrative
OPO	On Product Overlay	SOX	PHLX Semiconductor Sector Index
OVL	Overlay	SP	Single Patterning
PC	Personal Computer	STEM	Science, Technology, Engineering, and Mathematics

Investor Day 2024 - Abbreviations

Abbreviation	Meaning
tn	trillion
TSR	Total Shareholder Return
TW	Taiwan
VC	Voltage Contract
WpD	wafers per day
WpH	wafers per hour
YoY	Year on Year

The ASML logo is displayed in white, bold, sans-serif capital letters on a solid blue background. The background of the entire slide is a close-up, angled view of a semiconductor wafer, showing a complex grid of circuitry and various colored regions (blue, green, yellow) under bright, slightly blurred lighting.

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Thank you